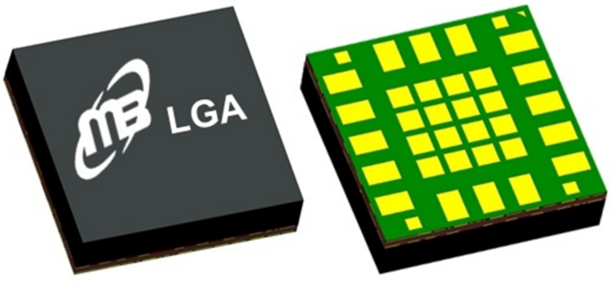
LGA

Package Data Sheet

Land Grid Array



Applications：

- RF, Wireless, GPS, Switch Devices
- Logic, Analog, and MEMS Sensors
- SiP Solutions
- Industry Micro-Controller

Features:

- Customized package size and leads in limited body size (1~ mm)
- Au, Cu, Ag-alloy bonding process capabilities
- Multi-chip capability for stack or flat lie
- Component surface mount capability
- Ni/Au, Ni/Pd-Au surface finish

Reliability Condition:

- Moisture Sensitivity Pre-condition :
  -MSL3: 192hrs@30°C/60% RH
  -MSL1: 168hrs@85°C/85% RH
- Temperature Cycle: 500 cycles @ -65°C /+150°C
- Highly Accelerated Temp and Humidity Stress Test: 96hrs @130°C/85% RH
- High Temperature Storage: 1000hrs@150°C

Package Outlines Dimensions:

Substrate Formats (mm)	Standard Sub. Thickness (mm)	Standard Sub. Layer	Mold Cap Thickness (mm)	Pkg Thickness (mm)
189*68 2 Block	Min: 0.150 Max: 0.360	2/4/6	0.375 0.550 0.750	>0.500

Notes: Package Size and Thickness is able customized , Do not limited above list